An apparatus for interconnecting a first die (402) and a second die (404) of a multi die device (400) includes a master circuit block (406) that interfaces with the first die of the multi die device a slave circuit block (408) that interfaces with the second die of the multi die device a first memory (416a 416e) in the slave circuit block a second memory (430a 430e) in the master circuit block and a plurality of µbumps (1 6) between the first die and the second die wherein the master circuit block and the slave circuit block are configured to identify one of the µbumps (3) as a faulty µbump and store a first value that corresponds with the identified faulty µbump in the first memory.